## 2.5V Drive Pch MOS FET

## RTQ035P02

## Structure

Silicon P-channel MOSFET

## Features

- 1) Low On-resistance.(80mΩ at 2.5V)
- 2) High Power Package.
- 3) High speed switching.
- 4) Low voltage drive.(2.5V)

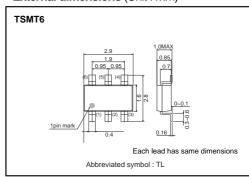
## Applications

DC-DC converter

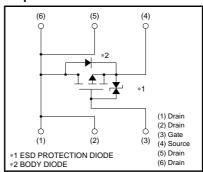
## Packaging specifications

| Туре      | Package                      | Taping |
|-----------|------------------------------|--------|
|           | Code                         | TR     |
|           | Basic ordering unit (pieces) | 3000   |
| RTQ035P02 | 0                            |        |

## ●External dimensions (Unit : mm)



## ●Equivalent circuit



## ● Absolute maximum ratings (Ta=25°C)

| Parameter                    |            | Symbol            | Limits      | Unit |  |
|------------------------------|------------|-------------------|-------------|------|--|
| Drain-source voltage         |            | Voss              | -20         | V    |  |
| Gate-source voltage          |            | Vgss              | ±12         | V    |  |
| Drain current                | Continuous | ΙD                | ±3.5        | А    |  |
|                              | Pulsed     | IDP *1            | ±17.5       | А    |  |
| Source current (Body diode)  | Continuous | ls                | -1          | А    |  |
|                              | Pulsed     | Isp *1            | -4          | А    |  |
| Total power dissipation      |            | P <sub>D</sub> *2 | 1.25        | W    |  |
| Channel temperature          |            | Tch               | 150         | °C   |  |
| Range of Storage temperature |            | Tstg              | -55 to +150 | °C   |  |

<sup>\*1</sup> Pw≤10μs, Duty cycle≤1% \*2 Mounted on a ceramic board

# ●Thermal resistance Parameter Symbol Limits Unit Channel to ambient Rth (ch-a) \* 100 °C / W

ROHM

<sup>\*</sup> Mounted on a ceramic board.

## ●Electrical characteristics (Ta=25°C)

| Parameter                               | Symbol               | Min. | Тур. | Max. | Unit | Conditions  |  |
|---|----------------------|------|------|------|------|---|--|
| Gate-source leakage                     | Igss                 | -    | _    | ±10  | μΑ   | Vgs=±12V, Vds=0V                                    |  |
| Drain-source breakdown voltage          | V <sub>(BR)DSS</sub> | -20  | -    | _    | V    | I <sub>D</sub> =-1mA, V <sub>G</sub> S=0V           |  |
| Zero gate voltage drain current         | IDSS                 | _    | -    | -1   | μΑ   | V <sub>DS</sub> =-20V, V <sub>GS</sub> =0V          |  |
| Gate threshold voltage                  | VGS(th)              | -0.7 | -    | -2.0 | V    | VDS=-10V, ID=-1mA                                   |  |
| Static drain-source on-state resistance | RDS(on)              | -    | 50   | 65   | mΩ   | In=-3.5A, Vgs=-4.5V                                 |  |
|   |                      | -    | 55   | 70   | mΩ   | ID=-3.5A, VGS=-4V                                   |  |
|   |                      | _    | 80   | 100  | mΩ   | In=-1.75A, Vgs=-2.5V                                |  |
| Foward transfer admittance              | Y <sub>fs</sub>  *   | 3.5  | _    | _    | S    | VDS=-10V, ID=-3.5A                                  |  |
| Input capacitance                       | Ciss                 | _    | 1200 | _    | pF   |   |  |
| Output capacitance                      | Coss                 | -    | 200  | _    | pF   | V <sub>DS</sub> =-10V,V <sub>GS</sub> =0V<br>f=1MHz |  |
| Reverse transfer capacitance            | Crss                 | _    | 130  | _    | pF   |   |  |
| Turn-on delay time                      | td(on) *             | -    | 16   | -    | ns   | - ID=-2A<br>VDD≒-15V<br>VGS=-4.5V<br>R1=7.5Ω        |  |
| Rise time                               | tr *                 | _    | 40   | _    | ns   |   |  |
| Turn-off delay time                     | td(off) *            | _    | 55   | _    | ns   |   |  |
| Fall time                               | t <sub>f</sub> *     | -    | 30   | -    | ns   | $R_G=10\Omega$                                      |  |
| Total gate charge                       | Qg                   | -    | 10.5 | -    | nC   | V . 45V   |  |
| Gate-source charge                      | Qgs                  | -    | 2.0  | _    | nC   | VDD≒-15V<br>VGS=-4.5V<br>ID=-3.5A                   |  |
| Gate-drain charge                       | Qgd                  | ı    | 3.5  | -    | nC   |   |  |

<sup>\*</sup>PULSED

## ●Body diode characteristics (Source-drain) (Ta=25°C)

| Parameter       | Symbol | Min. | Тур. | Max. | Unit | Conditions     |
|-----------------|--------|------|------|------|------|----------------|
| Forward voltage | Vsp    | -    | _    | -1.2 | V    | Is=-1A, Vgs=0V |

## Electrical characteristic curves 1000 Static Drain–Source On–State Resistance Res(on)[ $m\Omega$ ] Static Drain–Source On–State Resistance Ros(on)[ $m\Omega$ ] Drain Current: -lp (A) 0.01 0.001 Gate-Source Voltage : -Vgs[V] $Drain\ Current: -I_D[A]$ Drain Current : -Ip[A] Fig.2 Static Drain-Source On-State Fig.1 Typical Transfer Characteristics Fig.3 Static Drain-Source On-State Resistance vs. Drain Current Resistance vs.Drain Current Static Drain–Source On–State Resistance Resistance Resistance Static Drain–Source On–State Resistance Res(on)[ $m\Omega$ ] :-lbr[A] Reverse Drain Current 0.0 Source-Drain Voltage : -Vsp[V] Drain Current : -Ib[A] Drain Current : -Ip[A] Fig.4 Static Drain-Source On-State Fig.6 Reverse Drain Current vs. Source-Drain Voltage Fig.5 Static Drain-Source On-State Resistance vs. Drain-Current Resistance vs. Drain-Current 10000 1000 Ta=25°C VDD=-Gate-Source Voltage: -Ves [V] RG=10Ω RG=10Ω Switching Time : t [ns] Capacitance : C [pF] 1000 100 10 L 0.0 1 L

Drain Current : -Ip[A]

Fig.8 Switching Characteristics

Drain-Source Voltage : -Vps[V]

Fig.7 Typical Capactitance

vs.Drain-Source Voltage

Total Gate Charge : Qg[nC]

Fig.9 Dynamic Input Characteristics

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## Measurement circuits

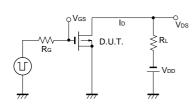


Fig.10 Switching Time Measurement Circuit

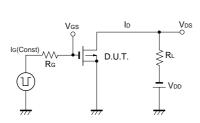


Fig.12 Gate Charge Measurement Circuit

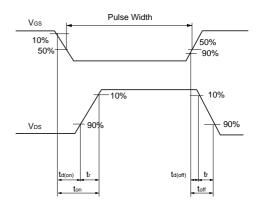


Fig.11 Switching Waveforms

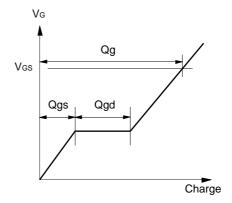


Fig.13 Gate Charge Waveforms

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